

Simulations for the Photon Target Cooled by Radiation

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1

Ti-alloy Target

- Positron Yield vs Target Thickness
- Energy Deposition Profile and PEDD
- Thermal Stress Induced by Pulse
- Stress in Target
- Average Deposited Power in Ti6Al4V Target
- Radiative Cooling
 - Basics of Radiative Cooling
 - 5 kW, $0.4 X_0$ Ti Rim
 - 5 kW. $0.4 X_0$ Ti Disk
 - 5 kW. $0.4 X_0$ Ti Rim + Cu Disk
 - Different Thicknesses of Ti-Alloy Target

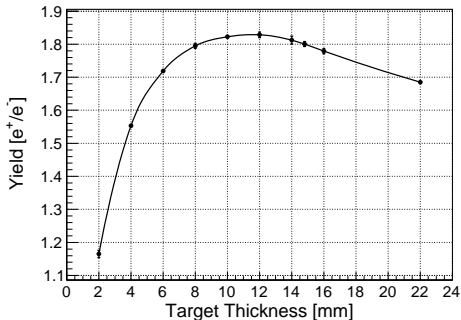
2

W-alloy Target

- Positron Yield vs Target Thickness
- PEDD and Total Deposited Power
- Peak Stress after Pulse
- Radiative Cooling
 - Different Thicknesses of W-Alloy Target
 - Thickness of Cu Disk

Positron Yield vs Thickness of Ti6Al4V Target

e^+ Yield vs Target Thickness

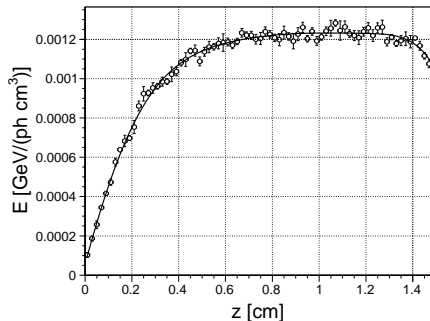


Source Parameters:

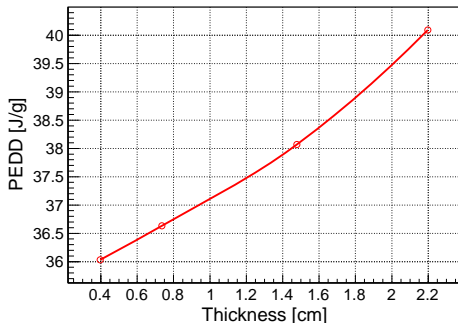
- $L_u = 231$ m, $K = 0.92$, $\lambda = 11.5$ mm
- $E_{e^-} = 120$ GeV
- Pulsed Flux Concentrator:
 $B_{max} = 3.2$ T, $R_{min} = 8.5$ mm
- DR Acceptance:
 $\epsilon_{nx} + \epsilon_{ny} \leq 70$ mm rad
 $\delta E/E < 1.5\%$ @ 5 GeV
 $\delta z_{bunch} < 34$ mm

Energy Deposition Profile and PEDD in Ti6Al4V Target

Energy Deposition Profile
along Beam Axis; $0.4 X_0$



PEDD vs
Target Thickness



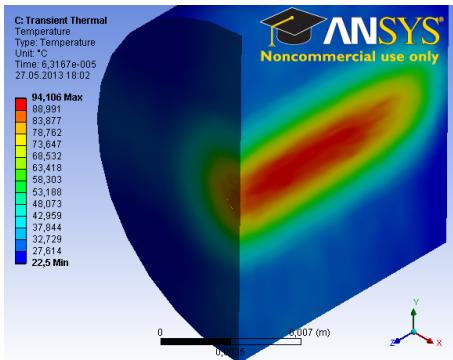
Rotation with 100 m/s; 554 ns bunch spacing

Bunch overlapping factor: 114

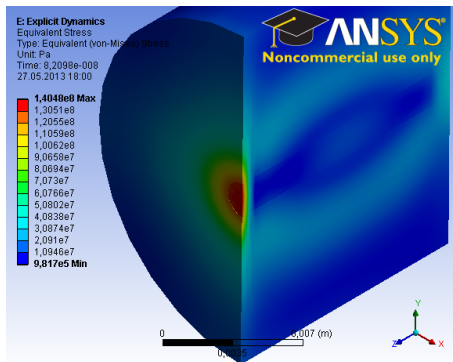
$$Y_{e^+} = 1.5 e^+/e^-$$

Thermal Stress Induced by Pulse. $0.4 X_0$ Ti, 120 GeV e^-

Temperature Distribution



Equivalent Stress



Stress in Target

$$\sigma = \sigma_{\text{mechanical}} + \sigma_{\text{eddy currents}} + \sigma_{\text{thermal}}$$

$$\sigma_{\text{thermal}} = \sigma_{\text{fast } \Delta T} + \sigma_{T_{\text{background}}}$$

$\sigma_{\text{mechanical}}$ is due to fast rotation: ~ 60 MPa for 0, 4X₀ Ti6Al4V,
 $R = 50$ cm, 2000 rpm

$\sigma_{\text{eddy currents}}$ is due to rotation in pulse magnetic field: ? MPa

$\sigma_{\text{fast } \Delta T}$ is due to fast temperature jump induced by a pulse:
 $\Delta T \sim 70$ °C in $\simeq 60 \mu\text{s} \Rightarrow 140$ MPa for 120 GeV e^-

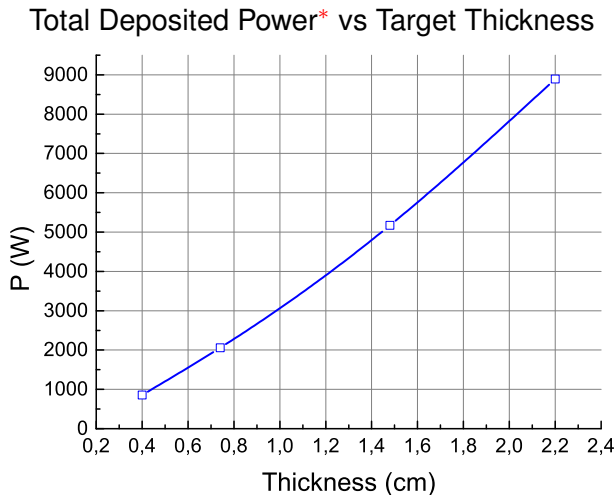
$\sigma_{T_{\text{background}}}$ is due to increased "background" (equilibrium) temperature distributed not equally over the target: depends on design of cooling system ($P \sim 5$ kW)

Ti6Al4V:

Fatigue Strength = 510 MPa

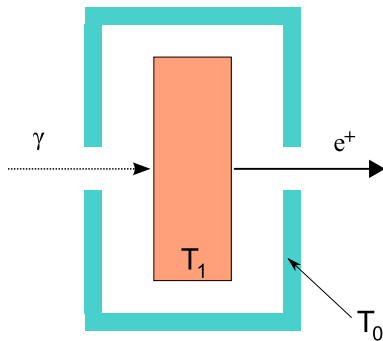
Tensile Yield Strength = 880 MPa

Average Deposited Power in Ti6Al4V Target



* 1312 bunches/pulse; 5 Hz repetition rate; $1.5 \text{ e}^+/\text{e}^-$

Basics of Radiative Cooling



Radiation heat transfer:

$$Q_R = \sigma \varepsilon F A (T_{target}^4 - T_{ambient}^4)$$

σ is the Stefan-Boltzman constant

ε is the **emissivity**

F is geometric form factor

A is the **area of radiating surface**

T_{target} is the temperature of "hot" target (T_1)

$T_{ambient}$ is the temperature of "cold" absorber (T_0) or ambient temperature

Simplified model of radiation-to-ambient has been used in ANSYS:
 $T_0 = 22\text{ }^\circ\text{C}$, $F = 1$, A – surface area of target (or target + additional cooler)

Equilibrium Temperature. 5 kW, 0.4 X_0 Ti Rim

Target Dimensions:

Radius $R = 50$ cm
(middle of the rim)

Thickness $d = 1.48$ cm

Width $w = 3.0$ cm

Emissivity $\epsilon = 0.25$

Deposited Power $P = 5170$ W

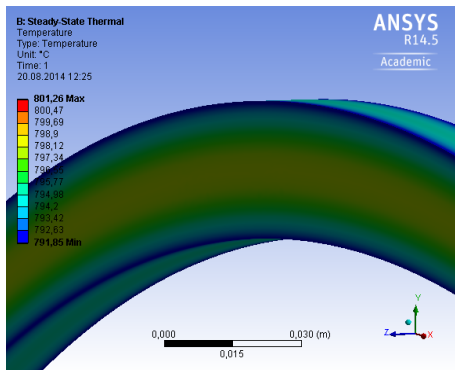
$T_{max} = 801$ °C

$T_{min} = 792$ °C

$\sigma_{max} = 5,5$ MPa

Equivalen (von-Mises) Stress

Temperature Distribution



Target Dimensions:

$$R = 50 \text{ cm}$$

$$d = 1.48 \text{ cm}$$

$$w = 3.0 \text{ cm}$$

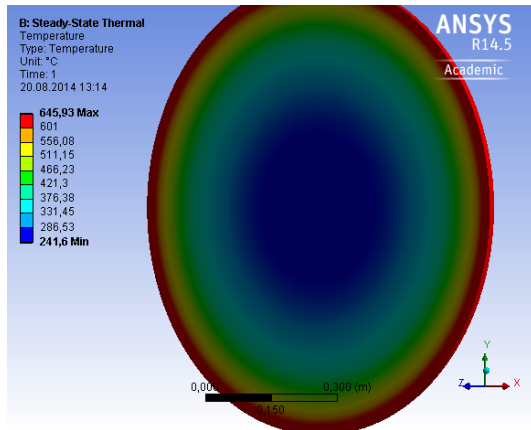
$$\epsilon = 0.25$$

$$P = 5170 \text{ W}$$

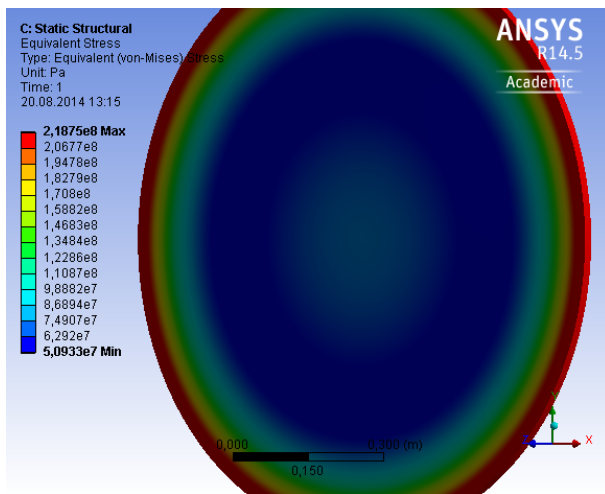
$$T_{\max} = 646 \text{ }^{\circ}\text{C}$$

$$T_{\min} = 242 \text{ }^{\circ}\text{C}$$

Temperature Distribution



Distribution of Equivalent Stress



$$\sigma_{max} = 219 \text{ MPa}$$

5 kW. 0.4 X_0 Ti Rim + Cu Disk

Target Dimensions:

$$R = 50 \text{ cm}$$

$$d = 1.48 \text{ cm}$$

$$w = 3.0 \text{ cm}$$

$$\epsilon_{Ti} = 0.25$$

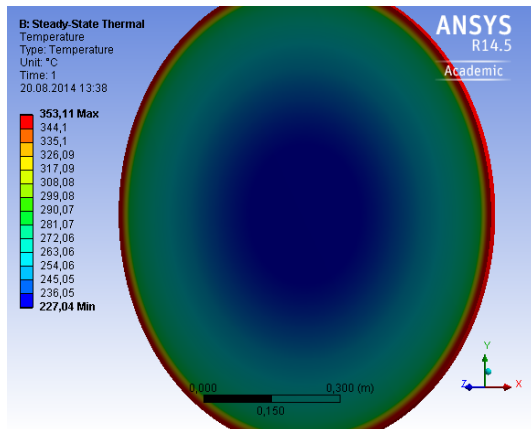
$$\epsilon_{Cu} = 0.9$$

$$P = 5170 \text{ W}$$

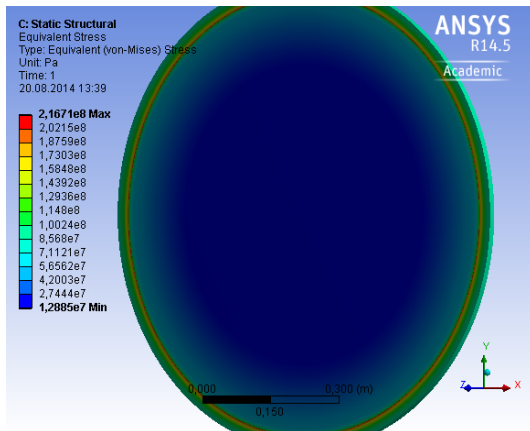
$$T_{max} = 353^\circ\text{C}$$

$$T_{min} = 227^\circ\text{C}$$

Temperature Distribution



Distribution of Equivalent Stress



$\sigma_{max} = 108 \text{ MPa}$ (in the middle of Ti)

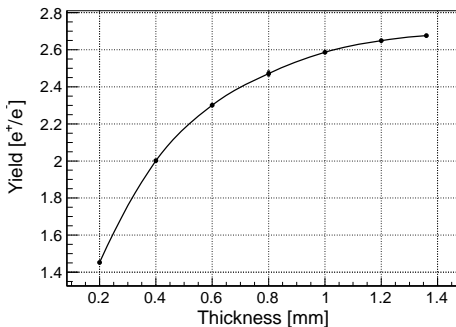
$\sigma_{Ti-Cu} = 217 \text{ MPa}$ (on the boundary between Ti and Cu)

Different Thicknesses of Ti-Alloy Target

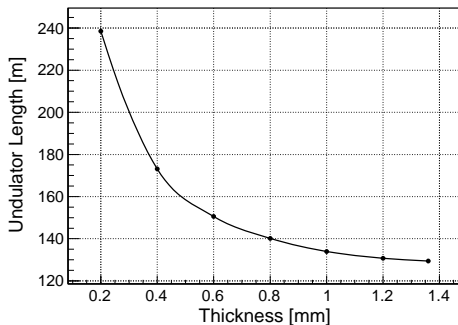
Thickness, mm	14,8	7,4	4,0
Power, kW	5,17	2,06	0,945
Ti rim			
T_{max} , °C	801	646	505
Ti disk			
T_{max} , °C	646	451	336
T_{min} , °C	242	113	63
σ_{max} , MPa	219	185	152
Ti rim + Cu disk			
T_{max} , °C	353	235	171
T_{min} , °C	227	135	86
σ_{max} , MPa	108	46	20
σ_{Ti-Cu} , MPa	217	136	98

e^+ Yield vs Thickness of W25Re Target. 120 GeV e^-

e^+ Yield vs Target Thickness

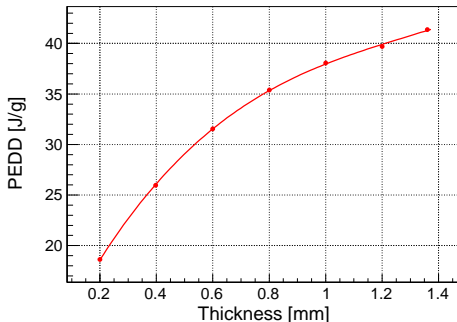


Undulator Length vs Target Thickness



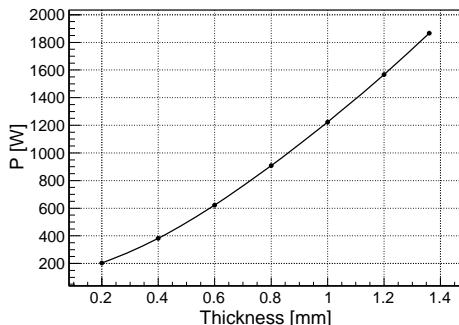
PEDD and Total Deposited Power for W25Re Target

PEDD vs Target Thickness



Rotation with 100 m/s
554 ns bunch spacing

Total Average Power vs Target Thickness

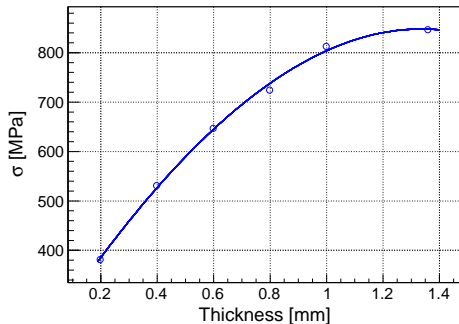


1312 bunches/pulse
5 Hz repetition rate

$$Y_{e^+} = 1.5 e^+/e^-$$

Peak Stress in W25Re Target after Pulse

"Hydrodynamic" Peak Stress per Pulse



Rotation with 100 m/s
554 ns bunch spacing

$$Y_{e^+} = 1.5 \text{ e}^+/\text{e}^-$$

$$\sigma = \alpha E \Delta T$$

α – coef. of thermal expansion;
 E – Young's modulus;
 ΔT – temperature rise per pulse:

$\Delta T = \text{PEDD} / c_p$,
 $c_p = 0.14 \text{ J/(g}^{\circ}\text{K)}$ – spec. heat capacity of W-alloy

$$\sigma \approx \sigma_{\text{static}} + \sigma_{\text{pulse}} \lesssim 550 \text{ MPa}$$

Not much space for σ_{static} left?

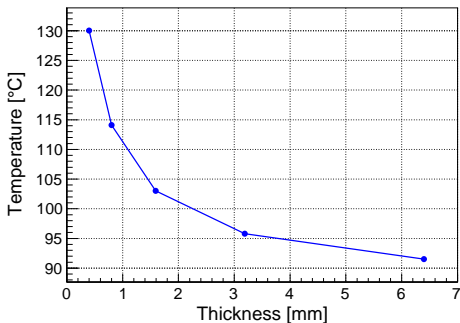
Different Thicknesses of W-Alloy Target

Thickness, mm	1,4	0,8	0,4
Power, kW	1,87	0,91	0,38
W rim + Cu disk			
T_{max} , °C	261	195	130
T_{min} , °C	80	51	29
σ_{max} , MPa	390	217	57
σ_{W-Cu} , MPa	459	270	112

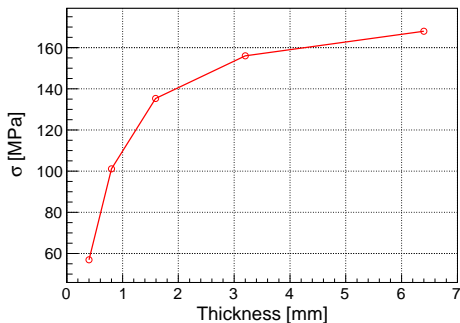
Thickness of Cu Disk

0,4 mm thick W ($0,12 X_0$); 950 W

W Temperature vs Cu Thickness



Stress in W vs Cu Thickness



*Water cooling of rotated target can be replaced by **radiative cooling***

- 4 mm Ti rim around Cu disk ($R \approx 50$ cm) could be an option

Expected equilibrium temperature is 170 °C and quasi-static equivalent stress is 20 MPa (without taking into account contribution of a fast dynamic stress induced by a pulse)

- Design studies for radiative cooling of W target needs more "efforts" (relatively small total deposit power in the target, thickness is very small)